

HSS81

Silicon Epitaxial Planar Diode for High Voltage Switching

REJ03G0568-0300

(Previous: ADE-208-175B)

Rev.3.00 Mar 22, 2005

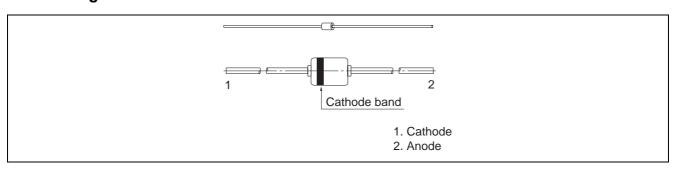
Features

- High reverse voltage. $(V_R = 150 \text{ V})$
- Suitable for 5 mm pitch high speed automatically insertion.
- Small glass package (MHD) enables easy mounting and high reliability.

Ordering Information

Type No.	Cathode band	Package Name	Package Code (Previous Code)
HSS81	Green	MHD	GRZZ0002ZC-A
			(MHD)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Peak reverse voltage	V _{RM} * ¹	200	V
Reverse voltage	V _R	150	V
Average rectified current	I ₀	150	mA
Peak forward current	I _{FM}	625	mA
Non-Repetitive peak forward surge current	I _{FSM} * ²	1	Α
Power dissipation	Pd	400	mW
Junction temperature	Tj	200	°C
Storage temperature	Tstg	-65 to +175	°C

Notes: 1. Reverse voltage in excess of peak reverse voltage may deteriorate electrical characteristic.

2. Within 1s forward surge current.

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_		200	nA	V _R = 150 V
	I _{R2}	1		100	μΑ	V _R = 200 V
Forward voltage	V _F	_		1.0	٧	I _F = 100 mA
Capacitance	С		1.5		pF	V _R = 0 V, f = 1 MHz
Reverse recovery time	t _{rr}	_	_	100	ns	$I_F = I_R = 30$ mA, $Irr = 3$ mA, $R_L = 100$ Ω

Main Characteristic

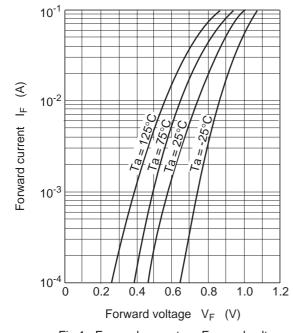


Fig.1 Forward current vs. Forward voltage

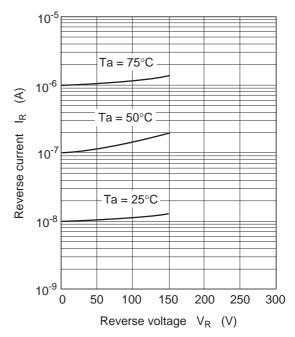
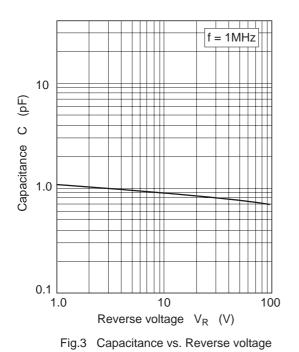
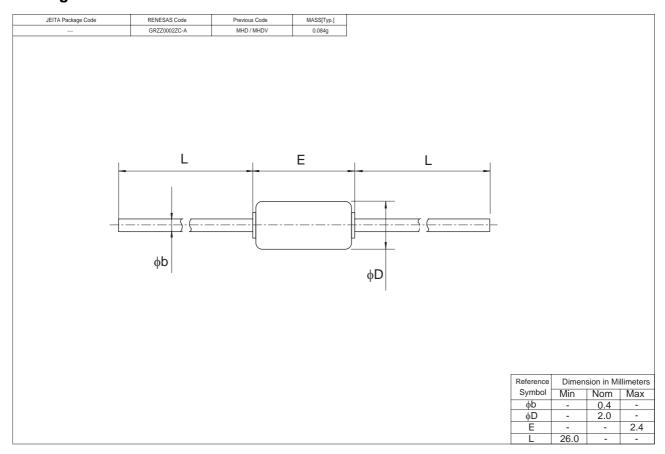


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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